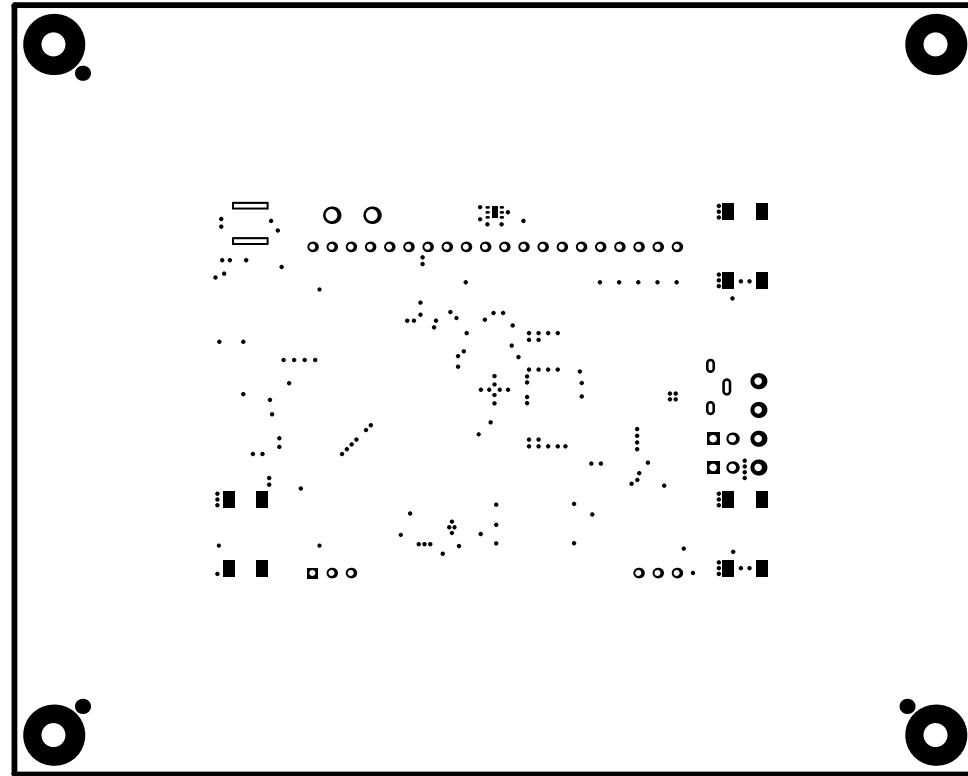
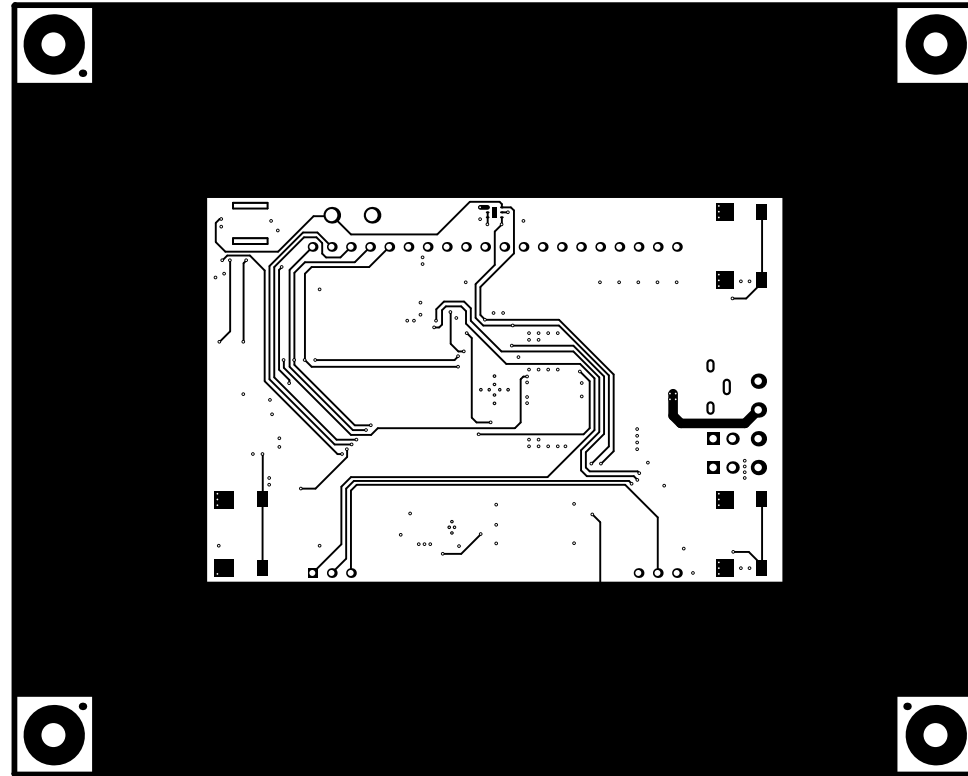


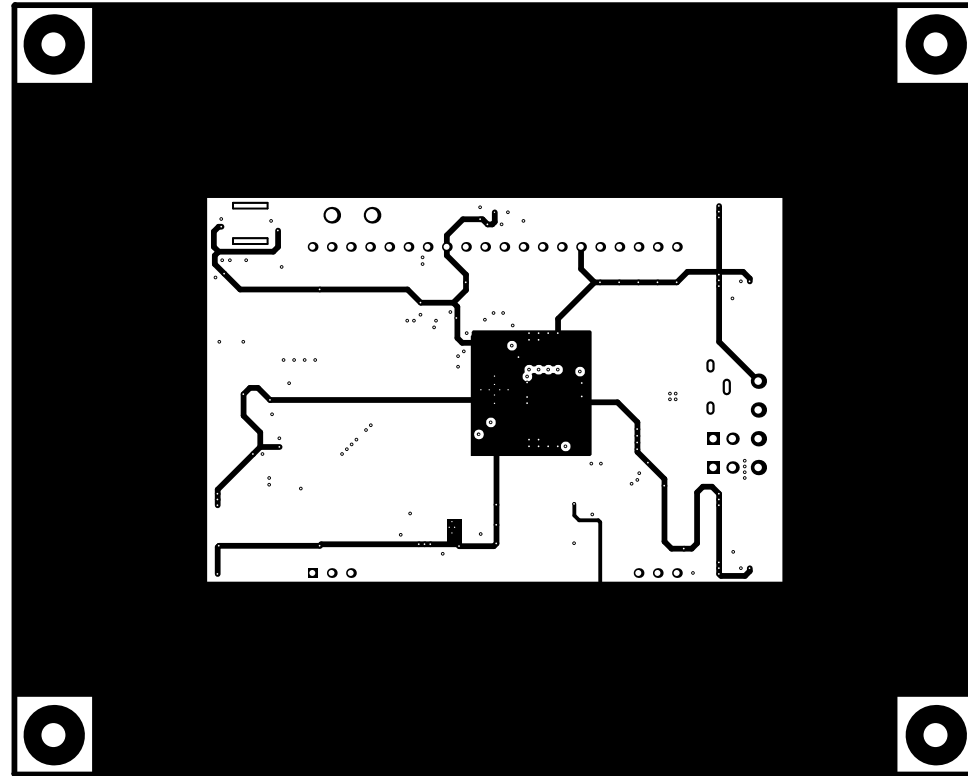
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: ISE4024	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TIDA-00373		
PLOT NAME = Top Overlay	GENERATED : 2/10/2015 7:01:40 PM	TEXAS INSTRUMENTS	



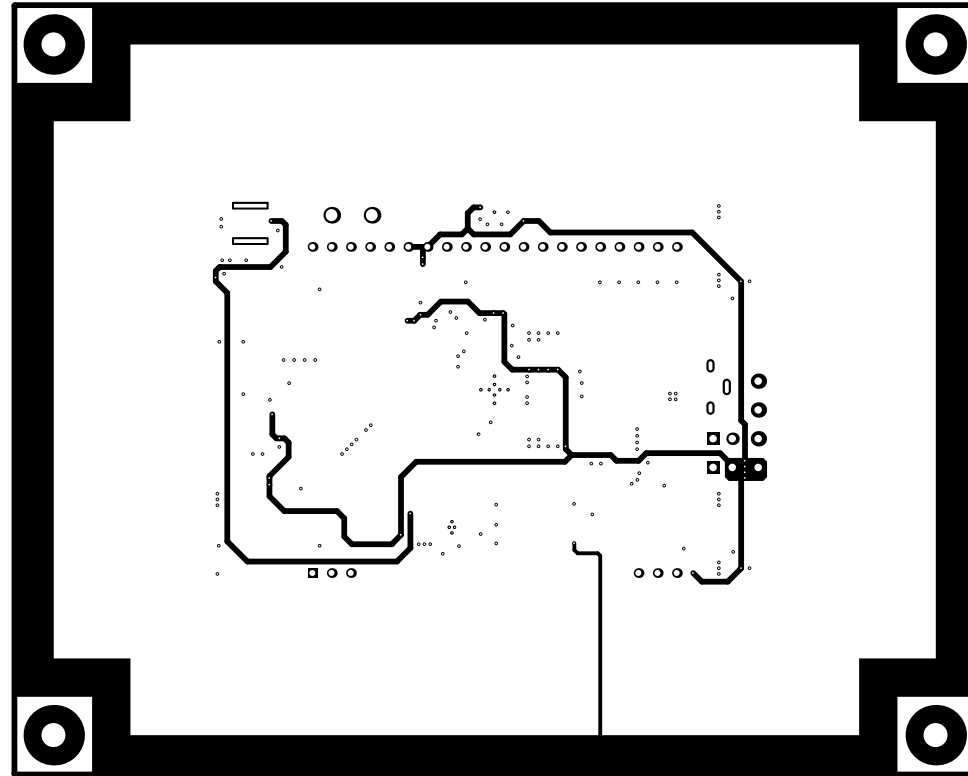
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: ISE4024	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TIDA-00373		
PLOT NAME = Top Solder Mask	GENERATED : 2/10/2015 7:01:41 PM	TEXAS INSTRUMENTS	



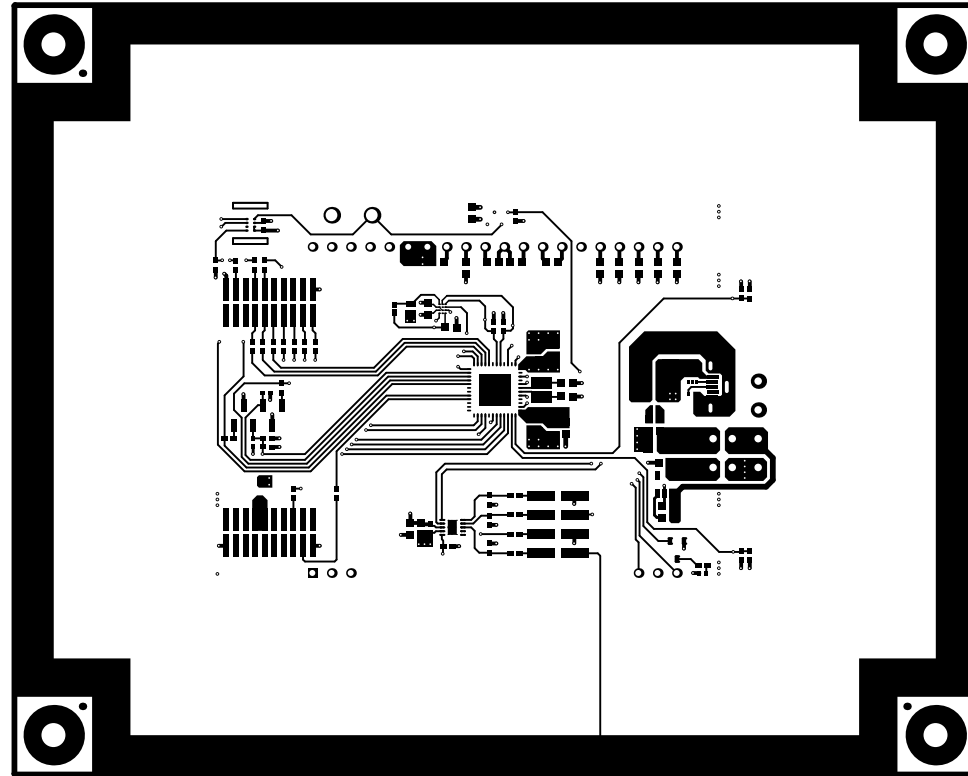
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: ISE4024	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Layer 1 - CINI - Top Layer	TIDA-00373		
PLOT NAME = Top Layer	GENERATED : 2/10/2015 7:01:42 PM	TEXAS INSTRUMENTS	



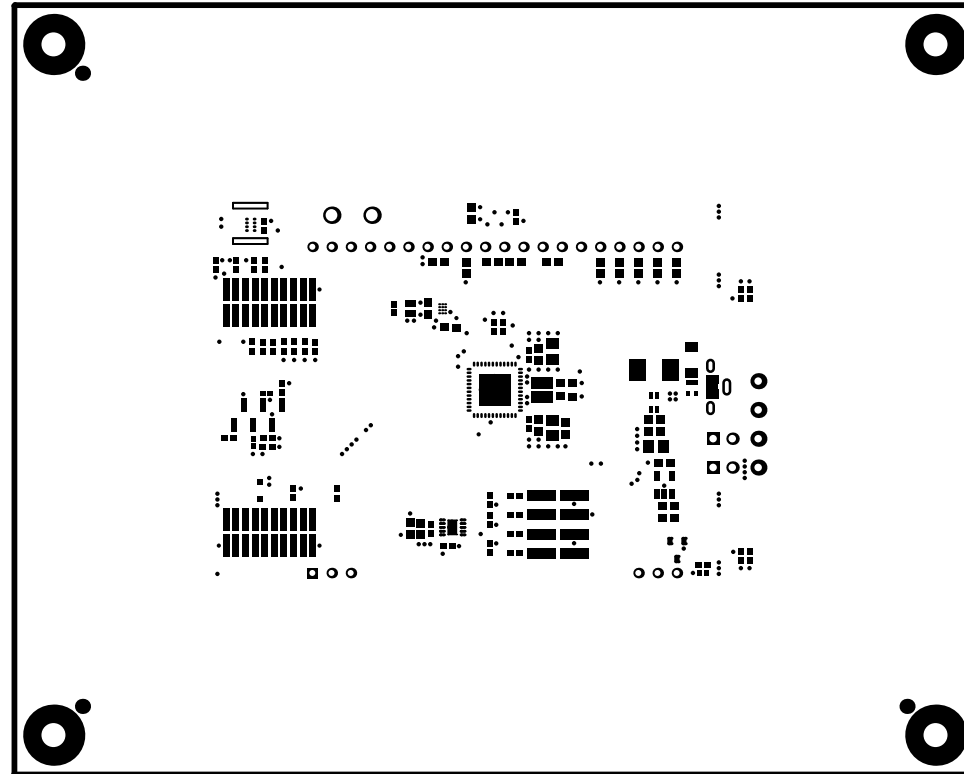
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: ISE4024	REV: E2	SUN REV: Not In VersionControl
LAYER NAME =	TIDA-00373		
PLOT NAME = MidLayer1	GENERATED : 2/10/2015 7:01:43 PM	TEXAS INSTRUMENTS	



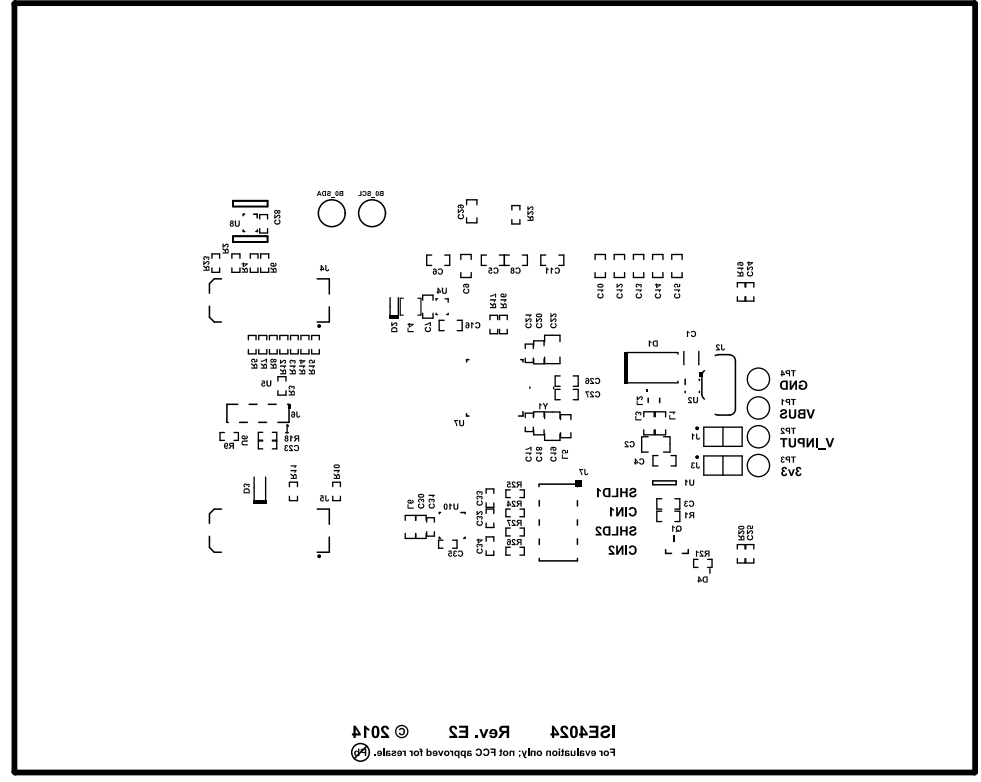
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: ISE4024	REV: E2	SUN REV: Not In VersionControl
LAYER NAME =	TIDA-00373		
PLOT NAME = MidLayer2	GENERATED : 2/10/2015 7:01:44 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: ISE4024	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Layer 4 - CIN2 - Bottom Layer	TIDA-00373		
PLOT NAME = Bottom Layer	GENERATED : 2/10/2015 7:01:45 PM	TEXAS INSTRUMENTS	

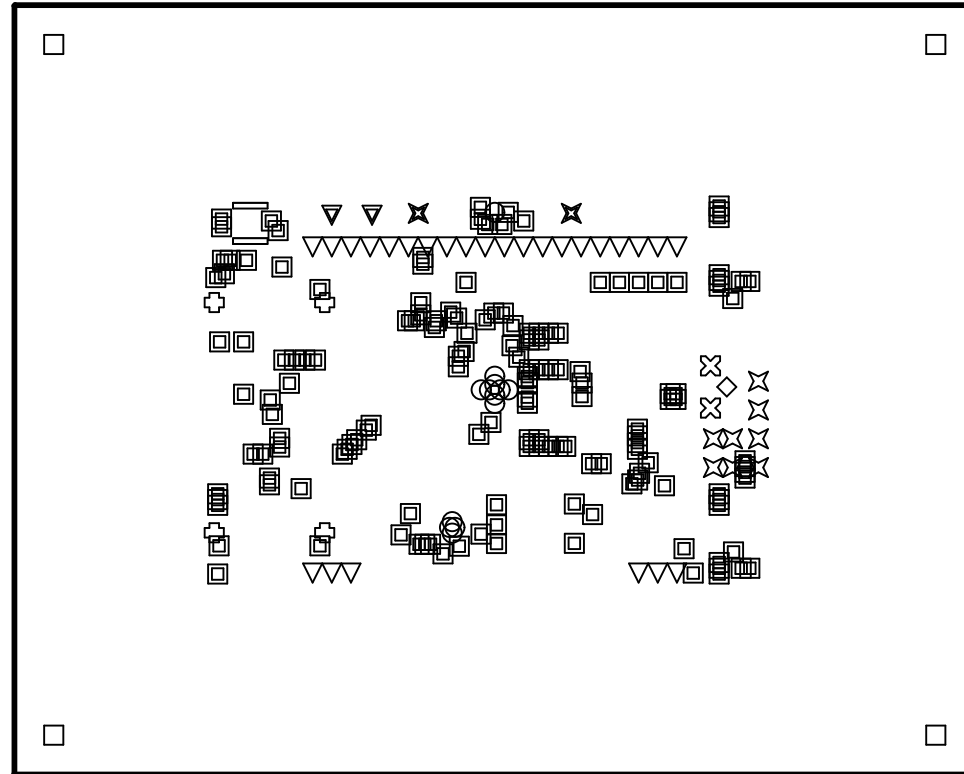


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: ISE4024	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TIDA-00373		
PLOT NAME = Bottom Solder Mask	GENERATED : 2/10/2015 7:01:46 PM	TEXAS INSTRUMENTS	



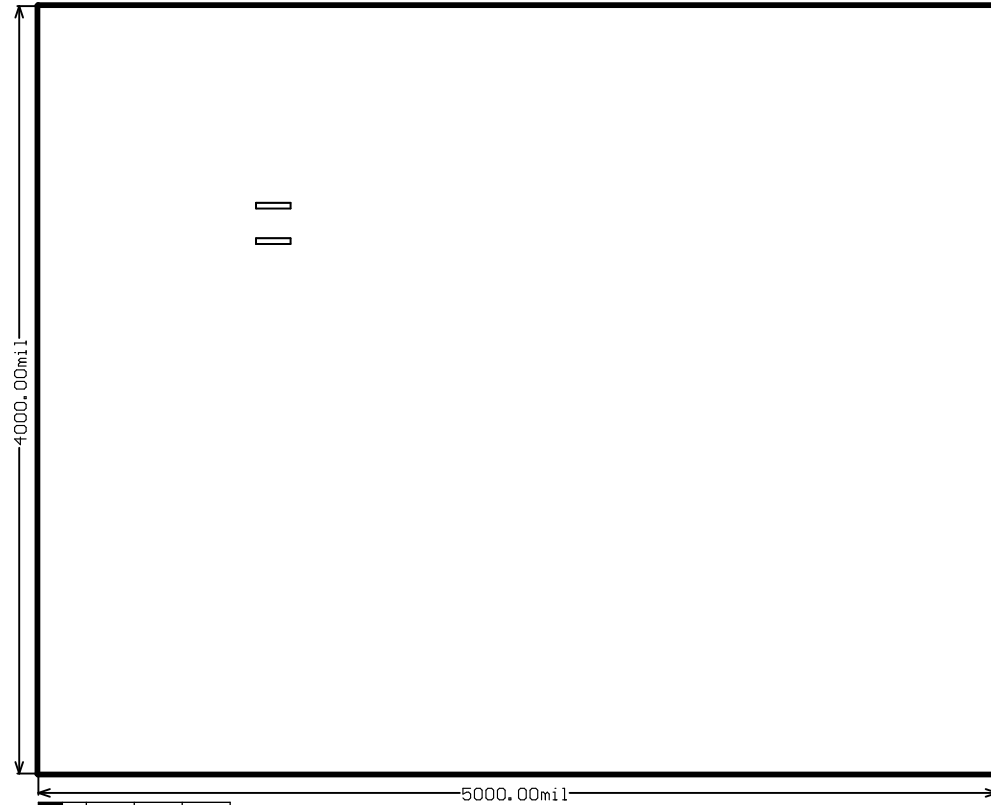
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: ISE4024	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TIDA-00373		
PLOT NAME = Bottom Overlay	GENERATED : 2/10/2015 7:01:47 PM	TEXAS INSTRUMENTS	





Symbol	Quantity	Finished Hole Size	Plated	Hole Type
⊕	4	57.09mil (1.450mm)	NPTH	Round
⊗	2	96.00mil (2.438mm)	NPTH	Round
○	13	7.87mil (0.200mm)	PTH	Round
■	151	10.00mil (0.254mm)	PTH	Round
▽	26	31.50mil (0.800mm)	PTH	Round
⊗	8	40.00mil (1.016mm)	PTH	Round
▽	2	63.00mil (1.600mm)	PTH	Round
□	4	125.98mil (3.200mm)	PTH	Round
⊗	2	19.69mil (0.500mm)	PTH	Slot
◇	1	19.69mil (0.500mm)	PTH	Slot
	213 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: ISE4024	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TIDA-00373		
PLOT NAME = Drill Drawing	GENERATED : 2/10/2015	7:01:48 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: ISE4024	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TIDA-00373		
PLOT NAME = Board Dimensions	GENERATED : 2/10/2015 7:01:49 PM	TEXAS INSTRUMENTS	

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